

# Specification of Thermoelectric Module

## TEFC1-20320

### Description

The 203 couples, 12 mm × 36 mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100/200 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

### Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

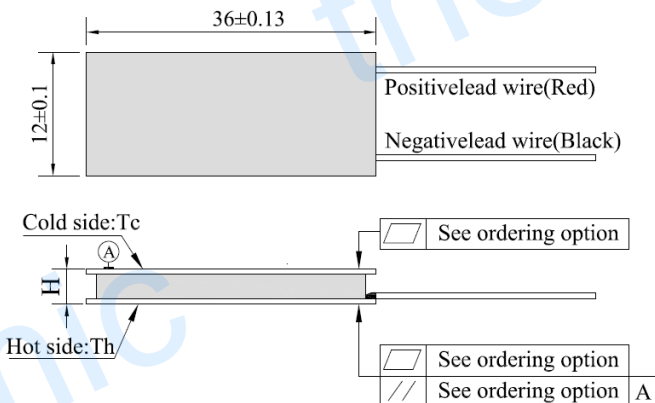
### Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

### Performance Specification Sheet

|                            |      |      |   |
|----------------------------|------|------|---|
| Th (°C)                    | 27   | 50   | Hot side temperature at environment: dry air, N <sub>2</sub>  |
| DT <sub>max</sub> (°C)     | 70   | 79   | Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side |
| U <sub>max</sub> (Voltage) | 25.5 | 27.5 | Voltage applied to the module at DT <sub>max</sub>  |
| I <sub>max</sub> (amps)    | 1.8  | 1.8  | DC current through the modules at DT <sub>max</sub>   |
| Q <sub>Cmax</sub> (Watts)  | 28.8 | 31.4 | Cooling capacity at cold side of the module under DT=0 °C   |
| AC resistance (ohms)       | 10.8 | 11.5 | The module resistance is tested under AC  |
| Tolerance (%)              | 5%   |      | For thermal and electricity parameters  |

### Geometric Characteristics Dimensions in millimeters



### Manufacturing Options

#### A. Solder:

1. T100: BiSn (T<sub>melt</sub>=138°C)
2. T200: CuSn (T<sub>melt</sub> = 227 °C)

#### B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant
4. Customer specify sealing

#### C. Ceramics:

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)
2. Aluminum Nitride (AlN)

#### D. Ceramics Surface Options:

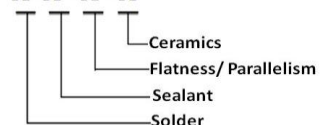
1. Blank ceramics (not metallized)
2. Metallized (Au plating)

### Ordering Option

| Suffix   | Thickness H (mm) | Flatness/Parallelism (mm) | Lead wire length(mm) Standard/Optional length |
|--|------------------|---------------------------|---|
| TF   | 0:2.6±0.1        | 0:0.1/0.13                | 50±1/Specify                                  |
| TF   | 1:2.6±0.05       | 1:0.08/0.1                | 50±1/Specify                                  |
| TF   | 2:2.6±0.025      | 2:0.05/0.08               | 50±1/Specify                                  |
| Eg. TF01: Thickness 2.6 ± 0.1(mm) and Flatness 0.08/0.1 (mm) |                  |                           |   |

### Naming for the Module

TEFC1- 20320- X -X - X - X



TEFC1- 20320-T100-NS -TF01 -AIO

T100: BiSn (T<sub>melt</sub>=138°C)

NS: No sealing

AIO: Alumina, white 96%

TF01: Thickness ± 0.1 (mm) and Flatness/Parallelism 0.08/0.1 (mm)

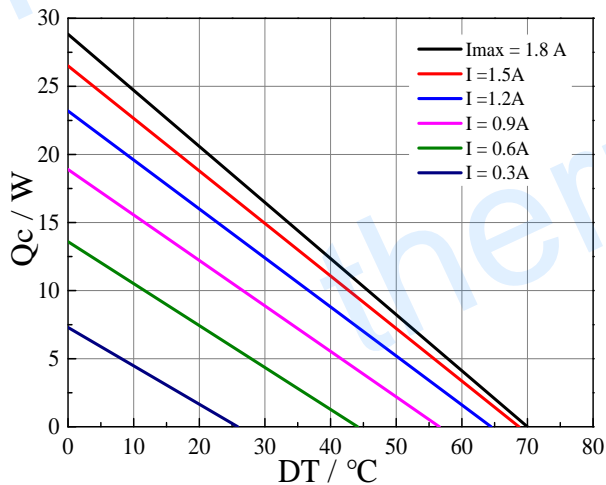
**Creative technology with fine manufacturing processes provides you the reliable and quality products**

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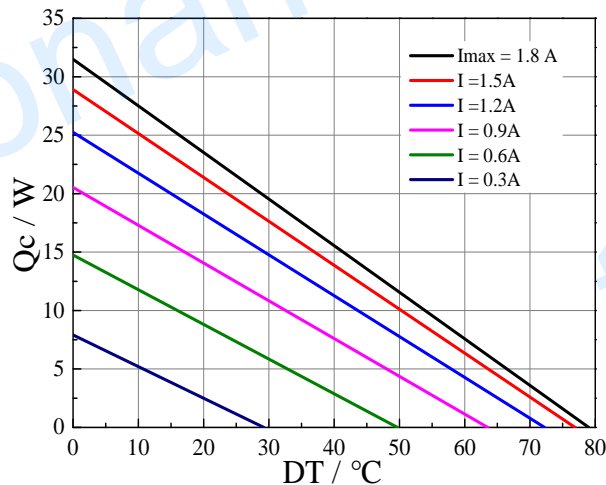
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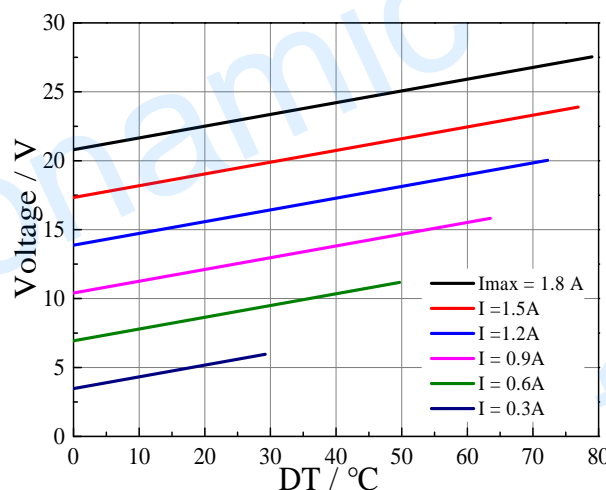
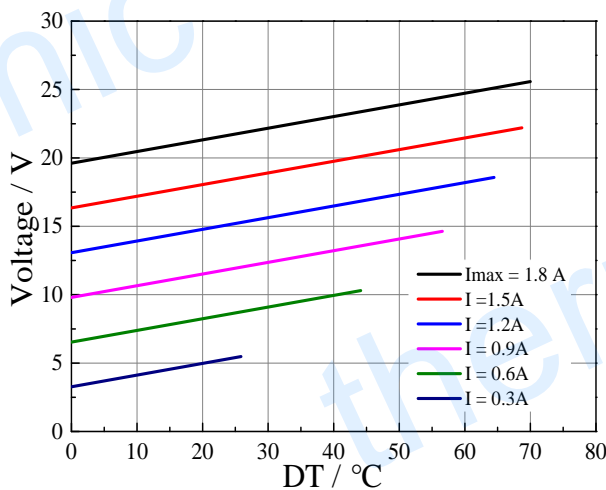
**Performance Curves at Th=27 °C**



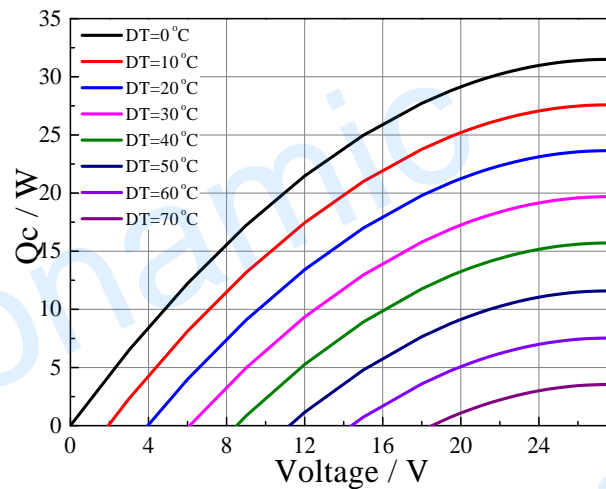
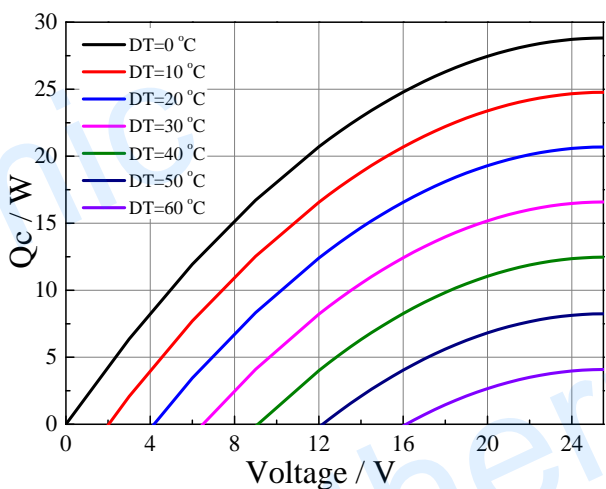
**Performance Curves at Th=50 °C**



Standard Performance Graph  $Q_c = f(DT)$



Standard Performance Graph  $V = f(DT)$

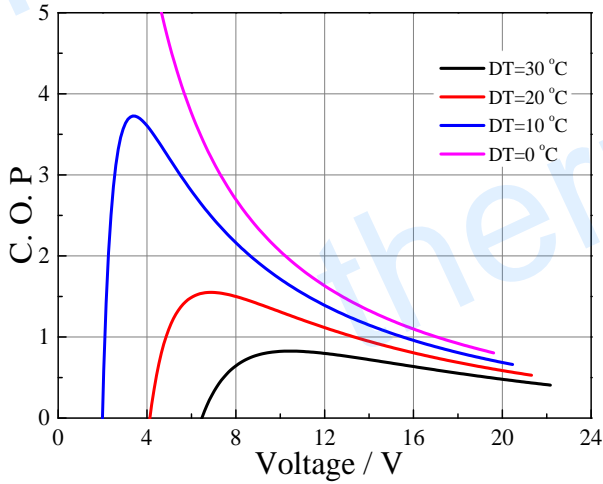


Standard Performance Graph  $Q_c = f(V)$

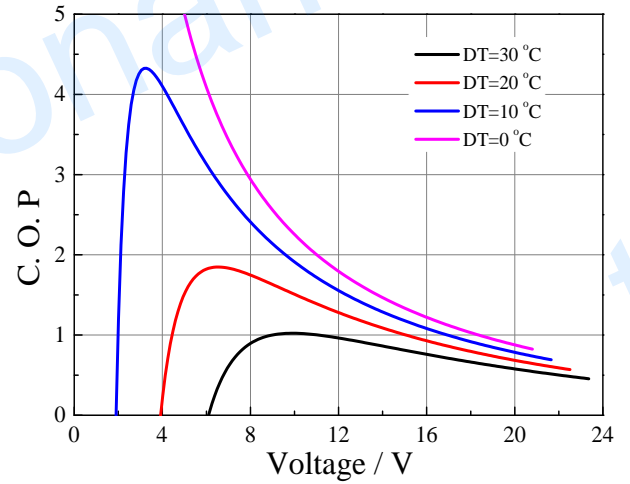
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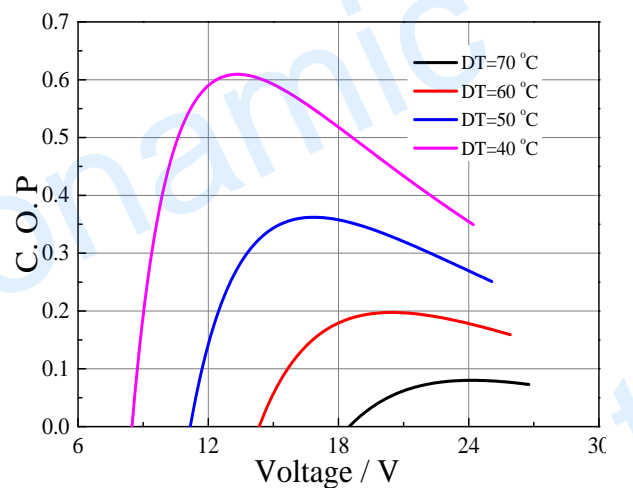
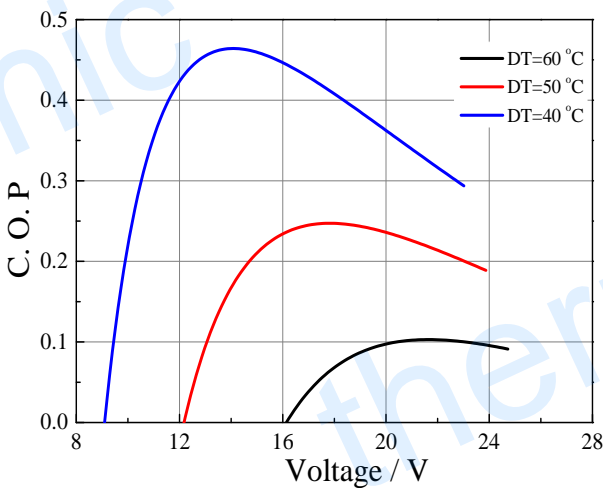
### Performance Curves at Th=27 °C



### Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

**Remark:** The coefficient of performance (COP) is the cooling power  $Q_c$ /Input power ( $V \times I$ ).

### Operation Cautions

- Cold side of the module stucked on the object being cooled
- Hot side of the module mounted on a heat radiator
- Operation below  $I_{max}$  or  $V_{max}$
- Work under DC

**Note:** All specifications subject to change without notice.